

SOT1390-5

wafer level chip-scale package, 12 bumps

18 April 2016

Package information

1. Package summary

Terminal position code	B
Package type descriptive code	WLCSP12
Package type industry code	WLCSP12
Package style descriptive code	WLCSP
Package style suffix code	NA
Mounting method type	S
Issue date	2-3-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.62	-	1.65	1.68	mm
E	package width	1.32	-	1.35	1.38	mm
A	seated height	0.485	-	0.525	0.565	mm
A ₂	package height	0.3	-	0.325	0.35	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	12	-	



2. Package outline

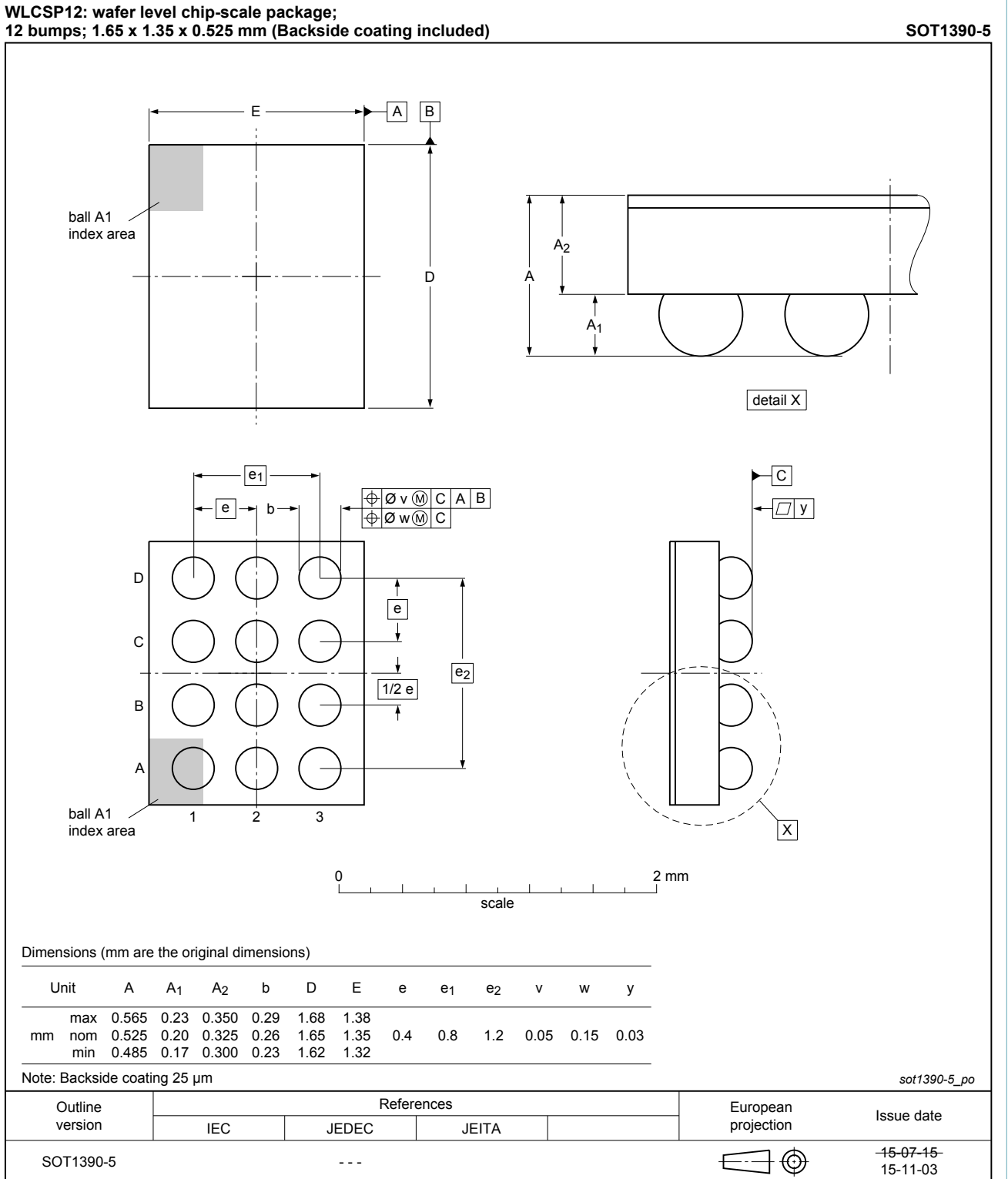


Fig. 1. Package outline WLCSP12 (SOT1390-5)

3. Legal information

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